



#### 4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

## **Product Summary**

V <sub>BR</sub> (Min)	I <sub>PP</sub> (Max)	C <sub>T</sub> (Typ)
4.5V	45A	2.1pF

#### **Description**

The D5V0P4UR6SO is a high-performance device suitable for protecting four high-speed I/Os. These devices are assembled in SOT26 package and have high ESD surge capability and low capacitance.

#### **Applications**

Typically used at high-speed ports such as USB 2.0, IEEE1394 (Firewire<sup>®</sup>, iLink™), Serial ATA, DVI, HDMI and PCI.





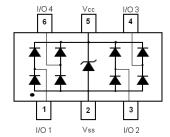
Top View

#### **Features**

- Low Clamping Voltage: Typical 7.5V at 12A 100ns, TLP, I/O to Vss; Typical 5.8V at 12A 100ns, TLP, Vcc to Vss
- IEC 61000-4-2 (ESD): Air ±30kV, Contact ±30kV
- IEC 61000-4-4 (EFT): ±80A (5/50ns)
- IEC 61000-4-5 (Lighting): 20A, I/O to V<sub>SS</sub>; 45A, V<sub>CC</sub> to V<sub>SS</sub>
- TLP Dynamic Resistance: 0.15Ω, I/O to V<sub>SS</sub>: 0.07Ω, V<sub>CC</sub> to V<sub>SS</sub>
- Low Channel Input Capacitance of 2.1pF Typical
- 4 Channels of ESD Protection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

- Case: SOT26
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Schematic
- Terminals Finish Matte Tin Pleated Leadframe.
   Solderable per MIL-STD-202, Method 208 <sup>3</sup>
- Weight: 0.016 grams (Approximate)



**Device Schematic** 

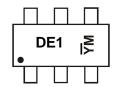
### **Ordering Information** (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
D5V0P4UR6SO-7	Standard	DE1	7	8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



DE1 = Product Type Marking Code

YM = Date Code Marking

Y = Year (ex: D = 2016)

M = Month (ex: 9 = September)

Note: "—" Represents Internal Code

Date Code Key

Year	20	16	20	17	20	18	20	19	20	20	20	21
Code		)	[		F	=	(	3	ŀ	1		
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

FireWire is a registered trademark of Apple Computer, Inc. iLink is a trademark of CEM Corporation.



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	Ipp	20	А	I/O to V <sub>SS</sub> , 8/20µs
Peak Pulse Current, per IEC 61000-4-5	Ipp	45	Α	V <sub>CC</sub> to V <sub>SS</sub> , 8/20µs
Peak Pulse Power, per IEC 61000-4-5	P <sub>PP</sub>	180	W	I/O to V <sub>SS</sub> , 8/20µs
Operating Supply Voltage (DC)	$V_{DC}$	3.6	V	V <sub>CC</sub> to V <sub>SS</sub>
ESD Protection – Contact Discharge, per IEC 61000-4-2	V <sub>ESD_CONTACT</sub>	±30	kV	I/O to V <sub>SS</sub> , V <sub>CC</sub> to V <sub>SS</sub>
ESD Protection – Air Discharge, per IEC 61000-4-2	V <sub>ESD_AIR</sub>	±30	kV	I/O to V <sub>SS</sub> , V <sub>CC</sub> to V <sub>SS</sub>
Operating Temperature	T <sub>OP</sub>	-55 to +85	°C	_
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C	_

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	$P_{D}$	300	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{ heta JA}$	417	°C/W

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

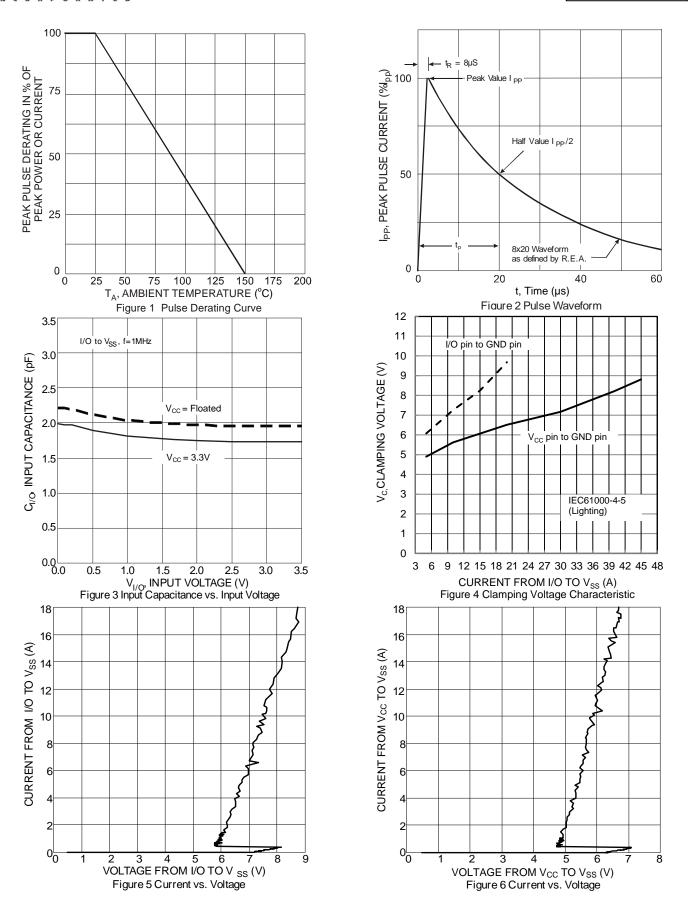
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	$V_{RWM}$	_	_	3.3	V	V <sub>CC</sub> to V <sub>SS</sub>
Reverse Leakage Current (Note 6)	I <sub>LEAK</sub>	_	_	5	μA	$V_{CC} = 3.3V$ , $V_{CC}$ to $V_{SS}$
Channel Leakage Current (Note 6)	I <sub>CH-LEAK</sub>	_	_	1	μA	$V_{I/O}$ = 3.3V, I/O to $V_{SS}$
Reverse Breakdown Voltage	$V_{BR}$	4.5	_	7	V	I <sub>BR</sub> = 1mA, V <sub>CC</sub> to V <sub>SS</sub>
Forward Clamping Voltage	VF	_	0.8	1.2	V	I <sub>F</sub> = 15mA, V <sub>SS</sub> to V <sub>CC</sub>
Reverse Clamping Voltage (Note 7)	V	_	6	_	V	$I_{PP} = 5A$ , I/O to $V_{SS}$ , 8/20 $\mu$ s
Reverse Clamping Voltage (Note 7)	$V_{C_5A}$	_	4.8	_	V	$I_{PP}$ = 5A, $V_{CC}$ to $V_{SS}$ , 8/20 $\mu$ s
ESD Clamping Voltage	V <sub>ESD</sub>	_	7.5	_	V	TLP, 12A, $t_P$ = 100ns, I/O to $V_{SS}$
L3D Clamping Voltage		_	5.8	_		TLP, 12A, $t_P = 100$ ns, $V_{CC}$ to $V_{SS}$
Dynamic Resistance	R <sub>DIF</sub>	_	0.15		Ω	TLP, 12A, $t_P$ = 100ns, I/O to $V_{SS}$
Dynamic Resistance		_	0.07	_	1 12	TLP, 12A, $t_P$ = 100ns, $V_{CC}$ to $V_{SS}$
Channel Innut Canaditanes	C <sub>I/O</sub>	_	2.1	2.5	pF	$V_{I/O} = 1.65V$ , $V_{CC} = 3.3V$ , $f = 1MHz$
Channel Input Capacitance		_	2.4	3.0	pF	$V_{I/O} = 1.65V$ , $V_{CC} = $ floated, $f = 1MHz$
	ΔC <sub>I/O</sub>		0.05		pF	$V_{SS} = 0V$ , I/O = 1.65V, $V_{CC} = 3.3V$ , f = 1MHz,
Variation of Channel Input Capacitance			0.05		рг	$I/O_x$ to $V_{SS} - I/O_y$ to $V_{SS}$
variation of original input dapacitance		_	0.04	_	pF	$V_{SS} = 0V$ , $I/O = 1.65V$ , $V_{CC} = floated$ , $f = 1MHz$ , $I/O_x$ to $V_{SS} - I/O_y$ to $V_{SS}$

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. website at http://www.diodes.com/package-outlines.html.

<sup>6.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>7.</sup> Clamping voltage value is based on an 8x20µs peak pulse current (IPP) waveform.



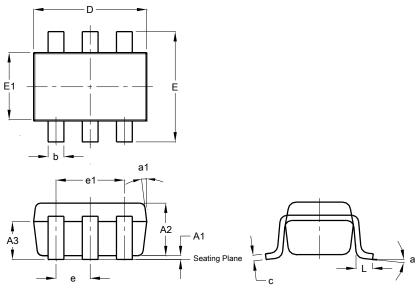




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



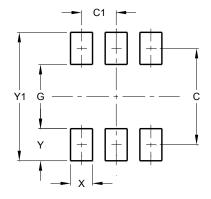


SOT26						
Dim	Min	Max	Тур			
A1	0.013	0.10	0.05			
A2	1.00	1.30	1.10			
A3	0.70	0.80	0.75			
b	0.35	0.50	0.38			
C	0.10	0.20	0.15			
D	2.90	3.10	3.00			
е	-	_	0.95			
e1	_	_	1.90			
Е	2.70	3.00	2.80			
E1	1.50	1.70	1.60			
L	0.35	0.55	0.40			
а	-	_	8°			
a1	ı	-	7°			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT26



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Υ	0.80
Y1	3.20



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